

# N-Channel 300 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$V_{DS}(V)$ $R_{DS(on)}(\Omega)$				
300	2.8 at V <sub>GS</sub> = 10 V	300			

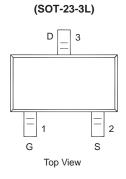
#### **FEATURES**

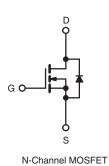
- DT-Trench MOSFET
- 100 % R<sub>g</sub> and UIS Tested
  Low Gate Charge

COMPLIANT

### **APPLICATIONS**

- LCD/LED TV
- Lighting





<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>A</sub> = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage		$V_{DS}$	300	V		
Gate-Source Voltage		$V_{GS}$	± 20	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		
Continuous Drain Current (T <sub>.I</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 25 °C		300			
Continuous Diain Current (1) = 150°C)	T <sub>A</sub> = 70 °C	I <sub>D</sub>	250	mA		
Pulsed Drain Current <sup>b</sup>	I <sub>DM</sub>	960				
Continuous Source Current (Diode Conduction) <sup>a</sup>	I <sub>S</sub>	300	mA			
Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C	D	0.98	w		
rower Dissipation	T <sub>A</sub> = 70 °C	P <sub>D</sub>	0.77	7		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a</sup>	t ≤ 5 s	В	75	125	°C/W	
Maximum Junction-to-Ambient	Steady State	$R_{thJA}$	125	190		
Maximum Junction-to-Foot	Steady State	R <sub>thJF</sub>	45	65		

#### Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. Pulse width limited by maximum junction temperature.

Rev. 1.0 1



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			Limits				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	<u> </u>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	300			V	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2		4	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zara Cata Valtaga Drain Current		V <sub>DS</sub> = 300 V, V <sub>GS</sub> = 0 V			1	μΑ	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 240 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 70 °C			75		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 15 \text{ V}, V_{GS} = 10 \text{ V}$	300			mA	
Drain-Source On-Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 150 mA		2.8	4	Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 150 mA		0.8		S	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 150 mA, V <sub>GS</sub> = 0 V		0.7	1.2	V	
Dynamic <sup>b</sup>							
Total Gate Charge	$Q_g$			2.5		nC	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 150 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 150 \text{ mA}$		0.6			
Gate-Drain Charge	Q <sub>gd</sub>			1.3			
Gate Resistance	$R_{g}$			1.3		Ω	
Switching	· · · · · · · · · · · · · · · · · · ·						
Input Capacitance	C <sub>iss</sub>			75			
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 150 \text{ V}, f = 1 \text{ MHz}$		12		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			6			
Turn-On Delay Time	t <sub>d(on)</sub>			6			
Rise Time	t <sub>r</sub>	$V_{DD}$ = 150 V, $R_L$ = 30 $\Omega$		4		ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 150$ mA, $V_{GEN} = 10$ V, $R_g = 6 \Omega$		11			
Fall Time	t <sub>f</sub>			23			

#### Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

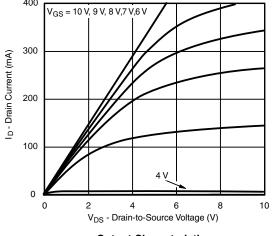
a. Pulse test: PW  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

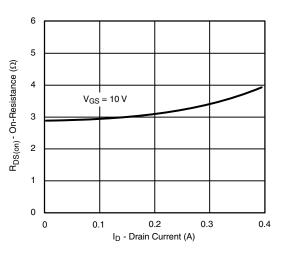




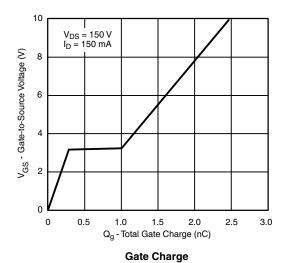
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

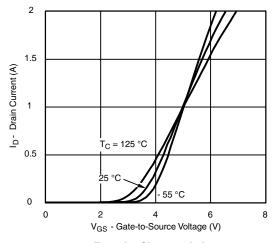


#### **Output Characteristics**

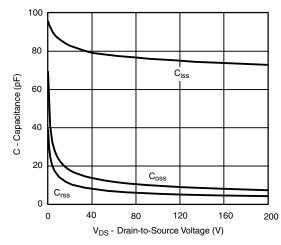


On-Resistance vs. Drain Current

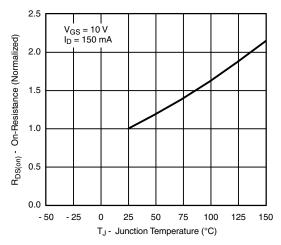




**Transfer Characteristics** 



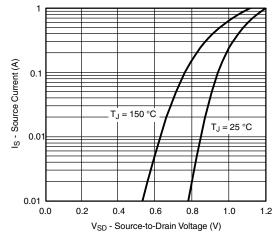
Capacitance

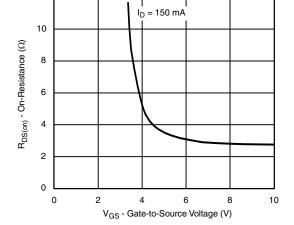


On-Resistance vs. Junction Temperature



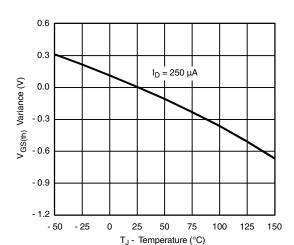
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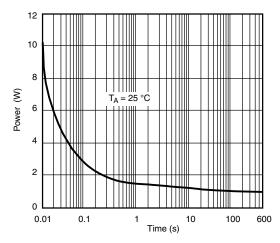


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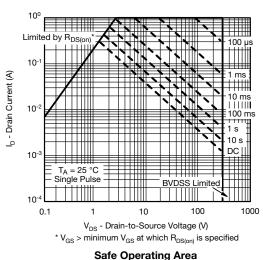
#### Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



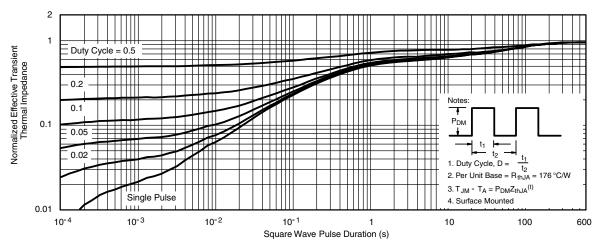
#### **Threshold Voltage**



Single Pulse Power



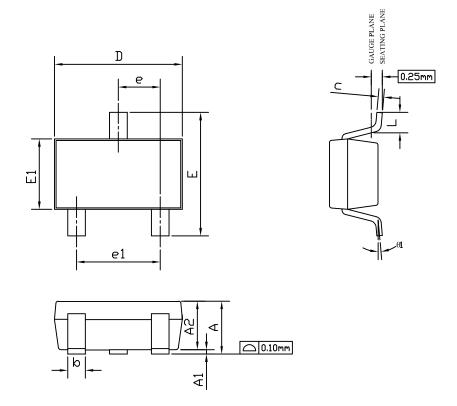
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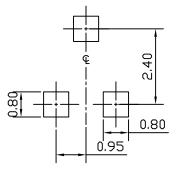
Normalized Thermal Transient Impedance, Junction-to-Ambient

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### SOT-23-3L PACKAGE OUTLINE



#### RECOMMENDED LAND PATTERN



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.85		1.25	0.033		0.049
A1	0.00		0.13	0.000		0.005
A2	0.70	1.00	1.15	0.028	0.039	0.045
b	0.30	0.40	0.50	0.012	0.016	0.020
c	0.08	0.13	0.20	0.003	0.005	0.008
D	2.80	2.90	3.10	0.110	0.114	0.122
E	2.60	2.80	3.00	0.102	0.110	0.118
E1	1.40	1.60	1.80	0.055	0.063	0.071
e	0.95 BSC				0.037 BSC	
e1	1.90 BSC			0.075 BSC		
L	0.30		0.60	0.012		0.024
θ1	0°	5°	8°	0°	5°	8°

UNIT: mm

#### NOTE

- 1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH OR GATE BURRS. MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 5 MILS EACH.
- 2. TOLERANCE  $\pm 0.100$  mm (4 mil) UNLESS OTHERWISE SPECIFIED.
- 3. DIMENSION L IS MEASURED IN GAUGE PLANE.
- 4. CONTROLLING DIMENSION IS MILLIMETER. CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.
- 5. ALL DIMENSIONS ARE IN MILLIMETERS.





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